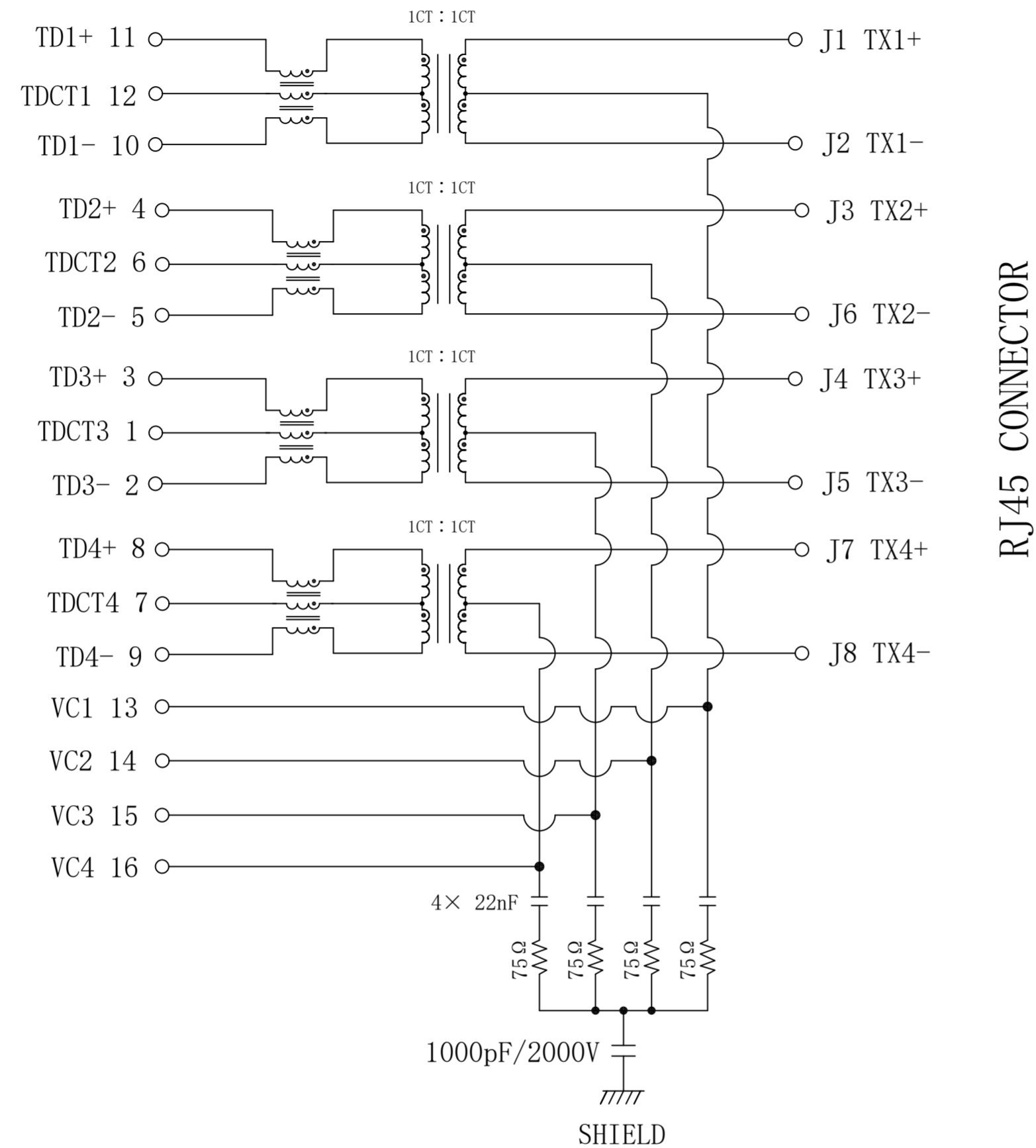


Schematic:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A6	REL		2023-03-21	

PC BOARD CONNECTIONS



ELECTRICAL SPECIFICATIONS @25°C

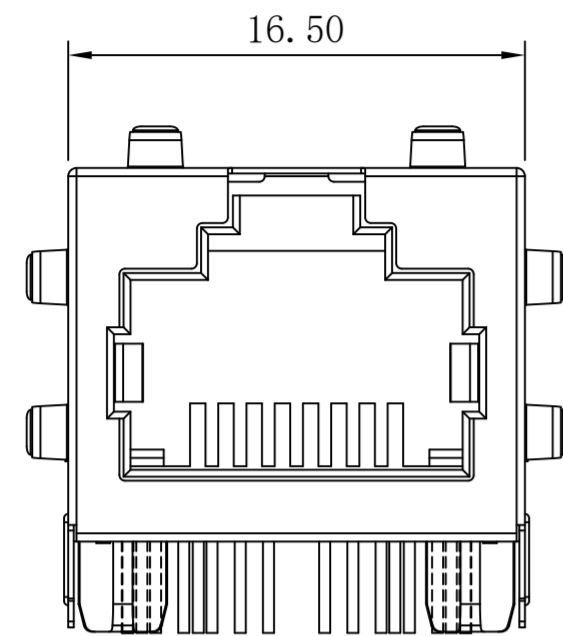
- Turn Ratio ($\pm 2\%$):
Pri:Sec = 1CT:1CT
- Inductance OCL:
160uH MIN @100KHz 0.1V 8mADC Bias.
- Insertion Loss:
-0.5dB MAX @1-50MHz
-1.0dB MAX @50-125MHz
-2.0dB MAX @125-300MHz
- Return Loss:
-16dB MIN @1-40MHz
-16+10LOG₁₀(f/40MHz) dB MIN @40-250MHz
- Cross talk:
-30dB MIN @1-125MHz
-25dB MIN @125-200MHz
-25dB MIN @200-300MHz
- Common Mode Rejection Ratio:
-30dB MIN @30-200MHz
- Balance DC Line current:
720mA MAX @57VDC Continuous;
1.2A MAX @57VDC For 200 Milliseconds.
- Isolation PHY SIDE To Line SIDE : 1500Vrms
- Operating Temperature Range: 0°C to 70°C.



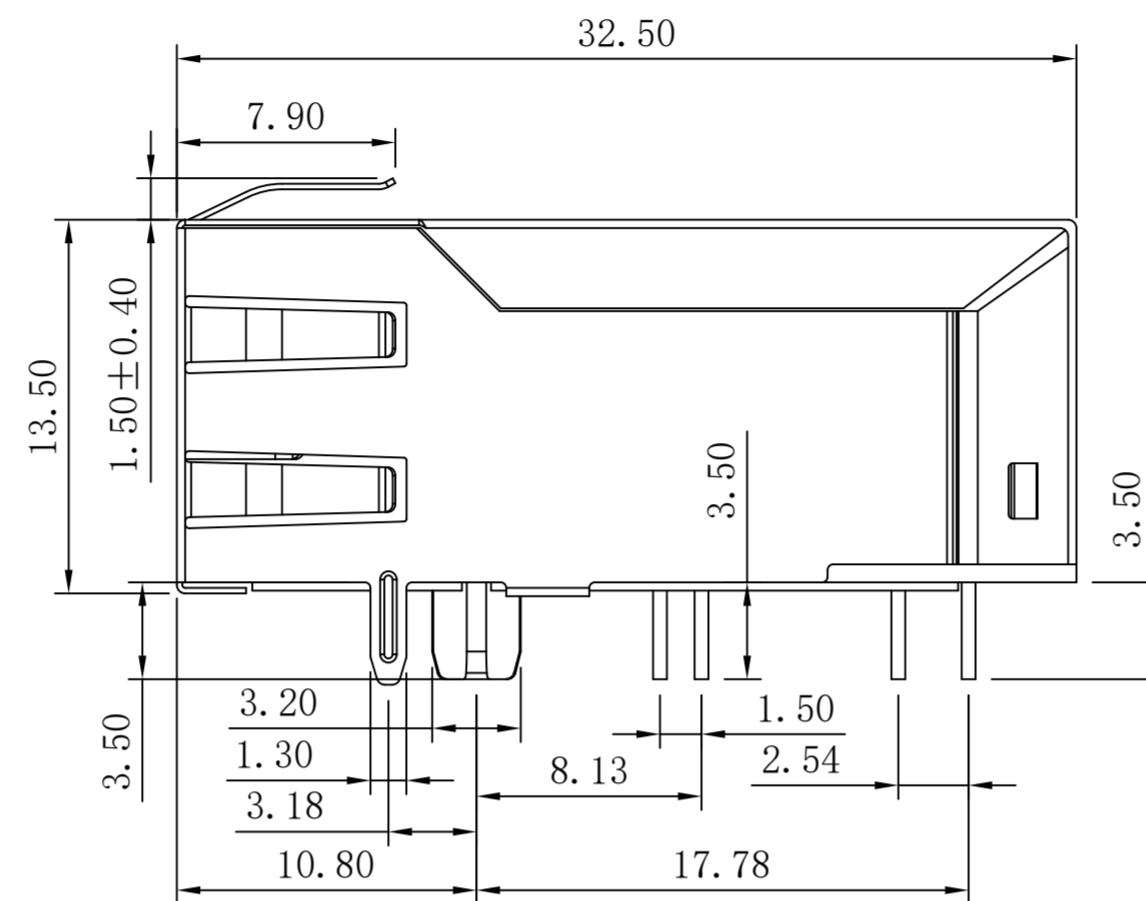
X:X	± 0.30	APPD: TOM	Summit Electronics BV	
X:XX	± 0.25	CHKD: JAMES		
X:XXX	± 0.05	DR: LEO	TITLE: RJ45 Connector with 5G Base-T Integrated Magnetics For PoE+ Application	
ANGLES	$\pm 1^\circ$	UNIT: mm	PART NO. :	SRJ101050020
	SCALE: 2/1	SHEET: 1/2	REV: A6	DWG NO. :

Mechanical :

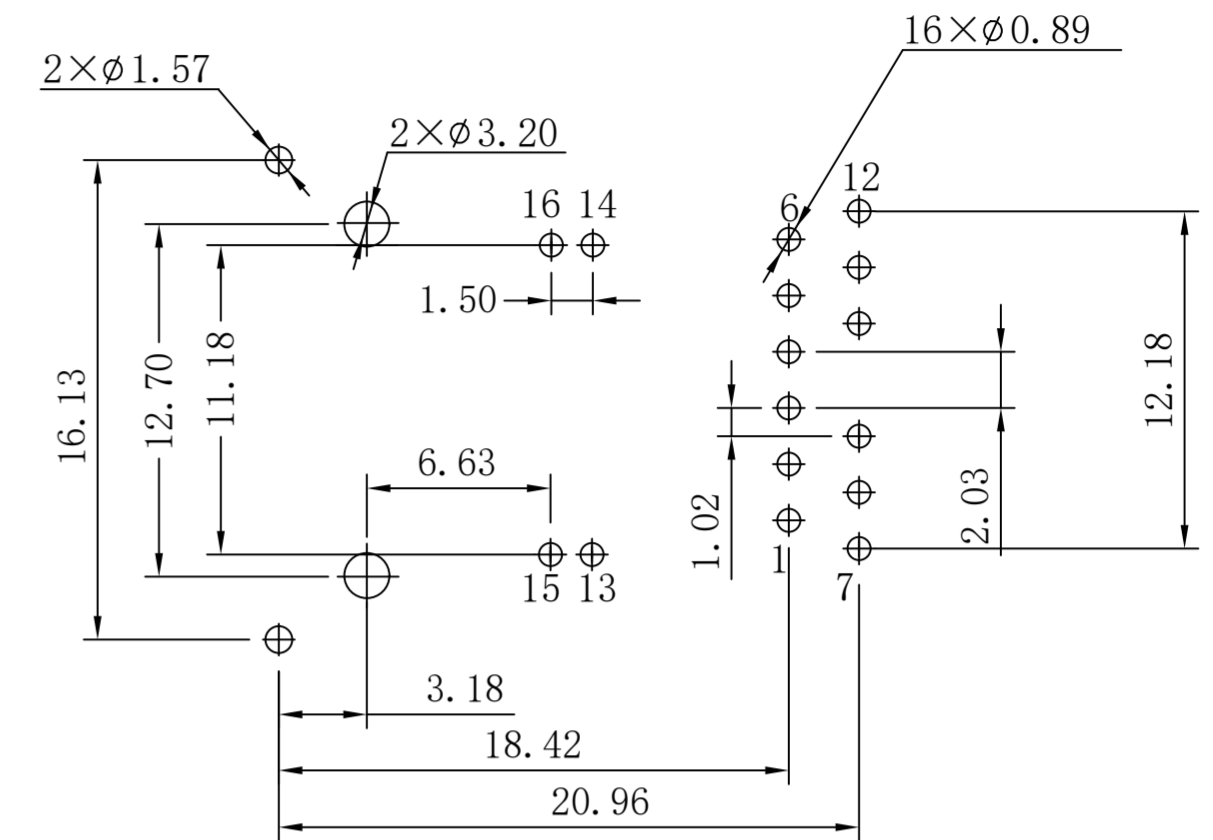
REV.	ECN NO.	DESCRIPTION	DATE	APPD
A6	REL		2023-03-21	



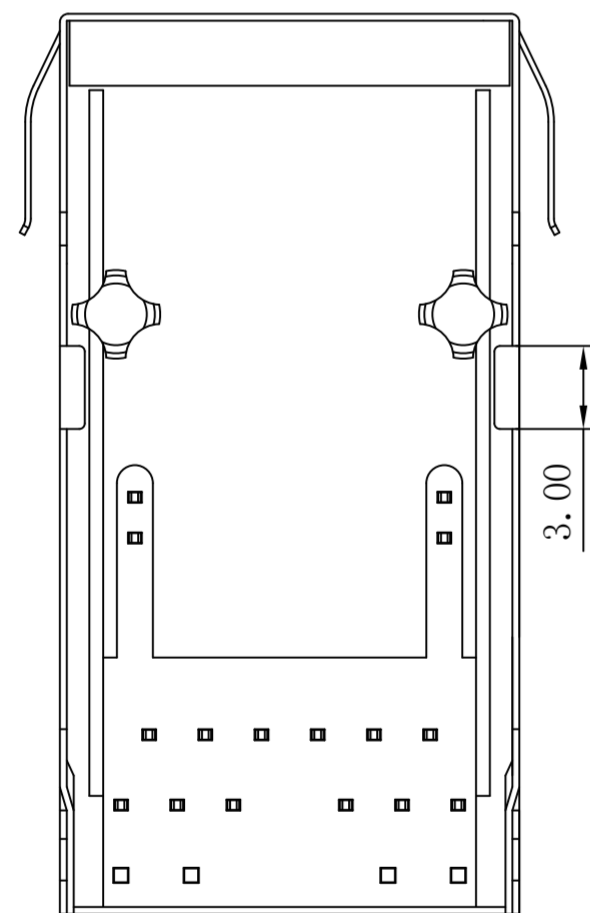
Front Side View



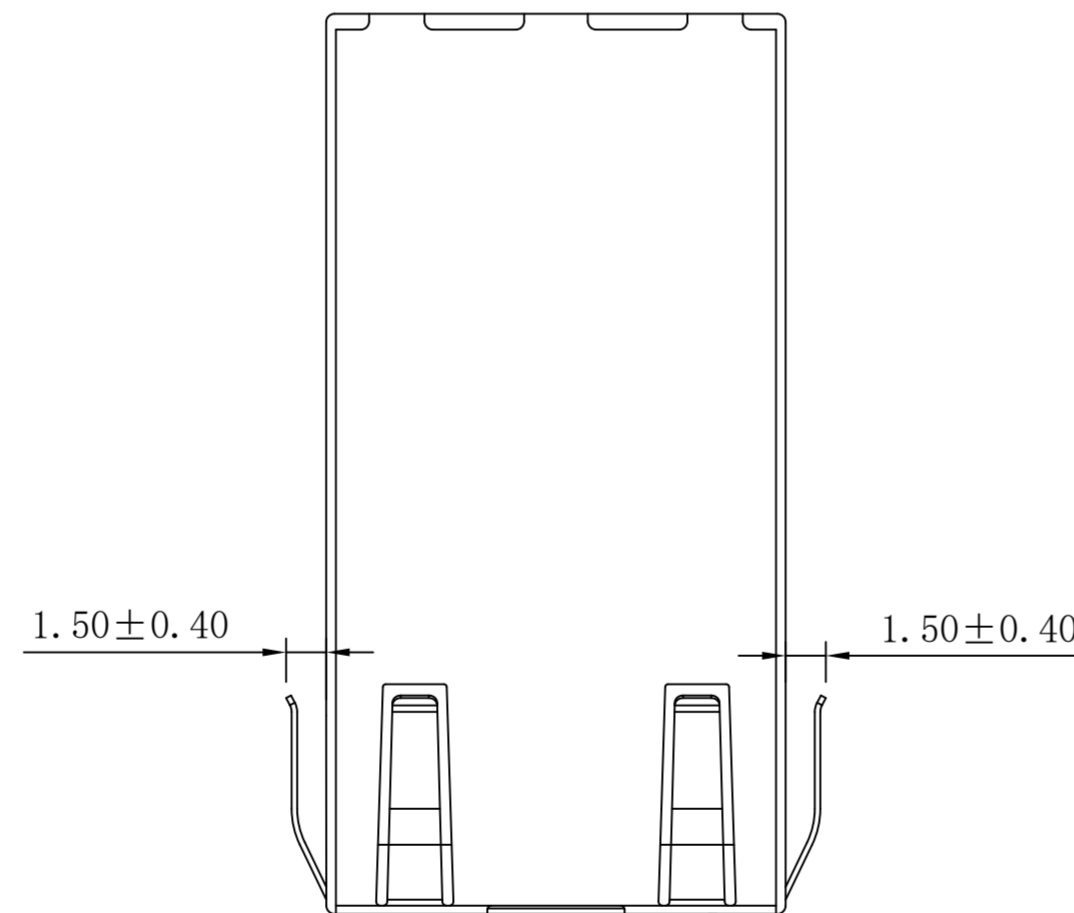
Left Side View



Suggested PCB Layout (Top View)



Bottom Side View



Top Side View

NOTES:

1. Designed to support application, such as SOHO (ADSL modems), LAN-on-Motherboard (LOM), hub and Switches.
2. Meets IEEE 802.3at specification
3. Connector Materials:
 Housing Material: Thermoplastic PBT+30%G. F UL94V-0
 Contact Material: Phosphor Bronze C5210R-EH Thickness=0.35mm
 Pins: Brass C2680R-H Thickness=0.35mm
 Shield: SUS 304 1/2EH Thickness=0.2mm
 Contact plating: Gold 6 micro-inches min. In contact area.
4. Wave solder tip temperature: 260°C, 5 Sec



X:X ±0.30	APPD: TOM	Summit Electronics BV
X:XX ±0.25	CHKD: JAMES	
X:XXX ±0.05	DR: LEO	
ANGLES ±1°	UNIT: mm	TITLE: RJ45 Connector with 5G Base-T Integrated Magnetics For PoE+ Application
		PART NO. : SRJ101050020
	SCALE: 2/1	SHEET: 2/2
	REV: A6	DWG NO. :